

312.5 MHz LVPECL Clock Generator

Features

■ One LVPECL Output Pair

■ Output Frequency: 312.5 MHz

■ External Crystal Frequency: 25 MHz

■ Low RMS Phase Jitter at 312.5 MHz, using 25 MHz crystal

(1.875 MHz to 20 MHz): 0.3 ps (typical)

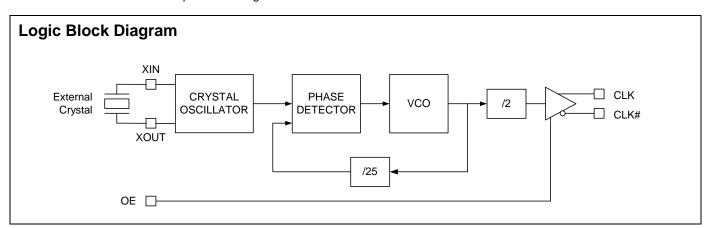
■ Pb-Free 8-Pin TSSOP Package

■ Supply Voltage: 3.3V or 2.5V

■ Commercial and Industrial Temperature Ranges

Functional Description

The CY2XP311 is a PLL (Phase Locked Loop) based high performance clock generator. It is optimized to generate 10 Gb Ethernet, SONET, and other high performance clock frequencies. It also produces an output frequency that is 12.5 times the crystal frequency. It uses Cypress's low noise VCO technology to achieve 0.3 ps typical RMS phase jitter, which meets both 10 Gb Ethernet and SONET jitter requirements. The CY2XP311 has a crystal oscillator interface input and one LVPECL output pair.



Pinouts

Figure 1. Pin Diagram - 8-Pin TSSOP

VDD	1	8	VDD
VSS	2	7	CLK
XOUT	3	6	CLK#
XIN	4	5	OE

Table 1. Pin Definition - 8-Pin TSSOP

Pin Number	Pin Name	I/O Type Description	
1, 8	VDD	Power	3.3V or 2.5V power supply.
2	VSS	Power	Ground
3, 4	XOUT, XIN	XTAL Output and Input	
5	OE	CMOS Input Output enable. When HIGH, the output is enabled. When LO output is high impedance	
6, 7	CLK#, CLK	LVPECL Output	Differential clock output



Frequency Table

Input	Output Frequency (MHz)	
Crystal Frequency (MHz)	PLL Multiplier Value	Output Frequency (MH2)
25	12.5	312.5

Absolute Maximum Conditions

Parameter	Description	Conditions	Min	Max	Unit
V_{DD}	Supply Voltage		-0.5	4.4	V
V _{IN} ^[1]	Input Voltage, DC	Relative to V _{SS}	-0.5	V _{DD} + 0.5	V
T _S	Temperature, Storage	Non operating	-65	150	°C
T _J	Temperature, Junction		_	135	°C
ESD _{HBM}	ESD Protection, Human Body Model	JEDEC STD 22-A114-B	2000 –		V
UL-94	Flammability Rating	At 1/8 in.	V-0		
$\Theta_{JA}^{[2]}$	Thermal Resistance, Junction to Ambient	0 m/s airflow	1	00	°C/W
		1 m/s airflow	,	91	
ı		2.5 m/s airflow		87	

Operating Conditions

Parameter	Description	Min	Max	Unit
V_{DD}	3.3V Supply Voltage	3.135	3.465	V
	2.5V Supply Voltage	2.375	2.625	V
T _A	Ambient Temperature, Commercial	0	70	°C
	Ambient Temperature, Industrial	-40	85	°C
T _{PU}	Power up time for all V_DD to reach minimum specified voltage (ensure power ramps is monotonic)	0.05	500	ms

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Notes
 The voltage on any input or I/O pin cannot exceed the power pin during power up.
 Simulated using Apache Sentinel TI software. The board is derived from the JEDEC multilayer standard. It measures 76 x 114 x 1.6 mm and has 4-layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metalization. No vias are included in the model.



DC Electrical Characteristics

Parameter	Description	Test Conditions	Min	Тур	Max	Unit
I _{DD}	Operating Supply Current with	$V_{DD} = 3.465V$, OE = V_{DD} , output unterminated	_	_	125	mA
	Output Unterminated	$V_{DD} = 2.625V$, OE = V_{DD} , output unterminated	_	_	120	mA
I _{DDT}	Operating Supply Current with	$V_{DD} = 3.465V$, OE = V_{DD} , output terminated	_	_	150	mA
	Output Terminated	V_{DD} = 2.625V, OE = V_{DD} , output terminated	_	_	145	mA
V _{OH}	LVPECL Output High Voltage	V_{DD} = 3.3V or 2.5V, R_{TERM} = 50Ω to V_{DD} – 2.0V	V _{DD} –1.15	-	V _{DD} –0.75	V
V _{OL}	LVPECL Output Low Voltage	V_{DD} = 3.3V or 2.5V, R_{TERM} = 50Ω to V_{DD} – 2.0V	V _{DD} –2.0	_	V _{DD} –1.625	V
V _{OD1}	LVPECL Peak-to-Peak Output Voltage Swing	V_{DD} = 3.3V or 2.5V, R_{TERM} = 50Ω to V_{DD} – 2.0V	600	_	1000	mV
V_{OD2}	LVPECL Output Voltage Swing (V _{OH} - V _{OL})	$V_{DD} = 2.5V, R_{TERM} = 50\Omega \text{ to } V_{DD} - 1.5V$	500	_	1000	mV
V _{OCM}	LVPECL Output Common Mode Voltage (V _{OH} + V _{OL})/2	$V_{DD} = 2.5V, R_{TERM} = 50\Omega \text{ to } V_{DD} - 1.5V$	1.2	_	_	V
I_{OZ}	LVPECL Output Leakage Current	Output off, OE = V _{SS}	-35	_	35	μΑ
V_{IH}	Input High Voltage, OE Pin		0.7*V _{DD}	_	V _{DD} +0.3	V
V_{IL}	Input Low Voltage, OE Pin		-0.3	_	0.3*V _{DD}	V
I _{IH}	Input High Current, OE Pin	$OE = V_{DD}$	_	_	115	μA
I _{IL}	Input Low Current, OE Pin	OE = V _{SS}	-50	_	_	μΑ
C _{IN^[5]}	Input Capacitance, OE Pin		_	15	_	pF
C _{INX} ^[5]	Pin Capacitance, XIN & XOUT		_	4.5	_	pF

AC Electrical Characteristics^[5]

Parameter	Description Conditons		Min	Тур	Max	Unit
F _{OUT}	Output Frequency		-	312.5	_	MHz
T _R , T _F ^[3]	Output Rise or Fall Time	20% to 80% of full output swing	-	0.5	1.0	ns
T _{Jitter(ϕ)} [6]	RMS Phase Jitter (Random)	312.5 MHz, (1.875 to 20 MHz)	-	0.3	_	ps
T _{DC} [7]	Output Duty Cycle	Measured at zero crossing point	45	_	55	%
T _{OHZ}	Output Disable Time	Time from falling edge on OE to stopped outputs (Asynchronous)	_	_	100	ns
T _{OE}	Output Enable Time	Time from rising edge on OE to outputs at a valid frequency (Asynchronous)	_	_	100	ns
T _{LOCK}	Startup Time	Time for CLK to reach valid frequency measured from the time $V_{DD} = V_{DD}(min.)$	-	_	5	ms

Recommended Crystal Specifications^[4]

Parameter	Description	Min	Max	Unit
Mode	Mode of Oscillation	Funda	mental	
F	Frequency	25	25	MHz
ESR	Equivalent Series Resistance	_	50	Ω
C _S	Shunt Capacitance	_	7	pF

Notes

- Refer to Figure 5 on page 4.
 Characterized using an 18 pF parallel resonant crystal.
 Not 100% tested, guaranteed by design and characterization.
 Refer to Figure 6 on page 5.
 Refer to Figure 7 on page 5.



Parameter Measurements

Figure 2. 3.3V Output Load AC Test Circuit

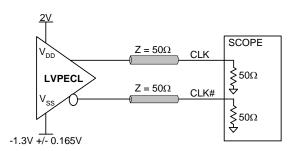


Figure 3. 2.5V Output Load AC Test Circuit

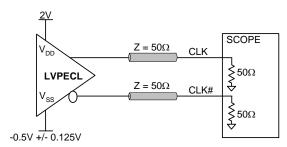


Figure 4. Output DC Parameters

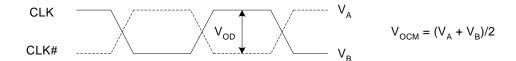


Figure 5. Output Rise and Fall Time

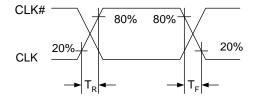




Figure 6. RMS Phase Jitter

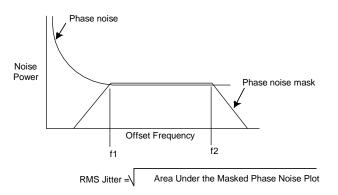


Figure 7. Output Duty Cycle

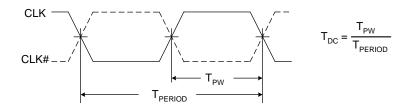
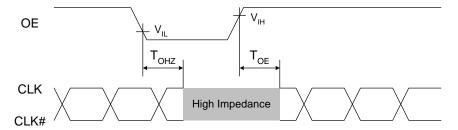


Figure 8. Output Enable Timing





Application Information

Power Supply Filtering Techniques

As in any high speed analog circuitry, noise at the power supply pins can degrade performance. To achieve optimum jitter performance, use good power supply isolation practices. Figure 9 illustrates a typical filtering scheme. 0.01 to 0.1 μF ceramic chip capacitors are located close to the VDD pins to provide a short and low impedance AC path to ground. A 1 to 10 μF ceramic or tantalum capacitor is located in the general vicinity of this device and may be shared with other devices. An acceptable alternative power supply configuration is shown in Figure 10.

Figure 9. Power Supply Filtering

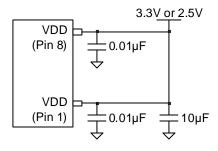
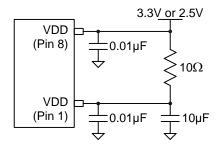


Figure 10. Alternative Power Supply Filtering

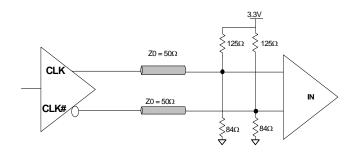


Termination for LVPECL Output

The CY2XP311 implements its LVPECL driver with a current steering design. For proper operation, it requires a 50 ohm dc termination on each of the two output signals. For 3.3V operation, this data sheet specifies output levels for termination to V_{DD} –2.0V. This same termination voltage can also be used for V_{DD} = 2.5V operation, or it can be terminated to V_{DD} -1.5V. Note that it is also possible to terminate with 50 ohms to ground (V_{SS}),

but the high and low signal levels differ from the data sheet values. Termination resistors are best located close to the destination device. To avoid reflections, trace characteristic impedance (Z_0) should match the termination impedance. Figure 11 shows a standard termination scheme.

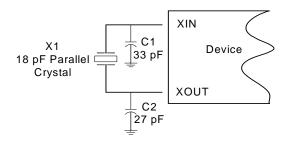
Figure 11. LVPECL Output Termination



Crystal Input Interface

The CY2XP311 is characterized with 18 pF parallel resonant crystals. The capacitor values shown in Figure 12 are determined using a 25 MHz 18 pF parallel resonant crystal and are chosen to minimize the ppm error. Note that the optimal values for C1 and C2 depend on the parasitic trace capacitance and are therefore layout dependent.

Figure 12. Crystal Input Interface



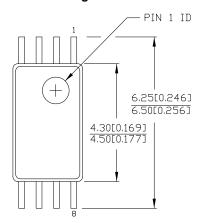


Ordering Information

Part Number	Package Type	Product Flow
CY2XP311ZXC	8-Pin TSSOP	Commercial, 0°C to 70°C
CY2XP311ZXCT	8-Pin TSSOP - Tape and Reel	Commercial, 0°C to 70°C
CY2XP311ZXI	8-Pin TSSOP	Industrial, -40°C to 85°C
CY2XP311ZXIT	8-Pin TSSOP - Tape and Reel	Industrial, -40°C to 85°C

Package Drawing and Dimensions

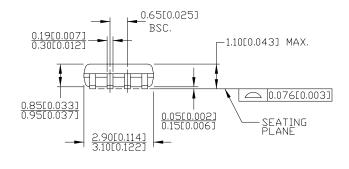
Figure 13. 8-Pin Thin Shrunk Small Outline Package (4.40 MM Body) Z8

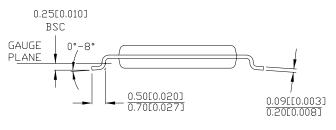


DIMENSIONS IN MM[INCHES] MIN. MAX.

REFERENCE JEDEC MO-153

PART #				
Z08.173	STANDARD PKG.			
ZZ08.173	LEAD FREE PKG.			





51-85093-*B



Document History Page

	Document Title: CY2XP311 312.5 MHz LVPECL Clock Generator Document Number: 001-59931					
Rev. ECN No. Submission Orig. of Change Description of Change		Description of Change				
**	2897143	3/22/2010	KVM	New data sheet		
*A	2915328	04/16/2010	KVM	Changed status from Preliminary to Final		

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Revised April 16, 2010

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